

# MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ310L

## JFET - VHF/UHF Amplifier Transistor

### N-Channel

#### Features

- Drain and Source are Interchangeable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	25	Vdc
Gate-Source Voltage	$V_{GS}$	25	Vdc
Gate Current	$I_G$	10	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

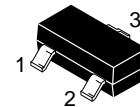
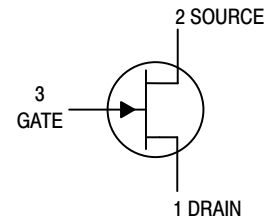
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 = 1.0 x 0.75 x 0.062 in.



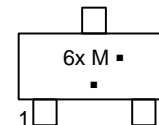
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SOT-23 (TO-236)  
CASE 318  
STYLE 10

#### MARKING DIAGRAM



6x = Device Code

x = U for MMBFJ309L, SMMBFJ309L

x = T for MMBFJ310L, SMMBFJ310L

M = Date Code\*

▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
MMBFJ309LT1G, SMMBFJ309LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBFJ310LT1G, SMMBFJ310LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBFJ310LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ310L

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Gate–Source Breakdown Voltage ( $I_G = -1.0\ \mu\text{Adc}$ , $V_{DS} = 0$ )	$V_{(BR)GSS}$	-25	–	–	Vdc
Gate Reverse Current ( $V_{GS} = -15\ \text{Vdc}$ ) ( $V_{GS} = -15\ \text{Vdc}$ , $T_A = 125^\circ\text{C}$ )	$I_{GSS}$	–	–	-1.0 -1.0	nAdc $\mu\text{Adc}$
Gate Source Cutoff Voltage ( $V_{DS} = 10\ \text{Vdc}$ , $I_D = 1.0\ \text{nAdc}$ )	$V_{GS(off)}$	-1.0 -2.0	–	-4.0 -6.5	Vdc

### ON CHARACTERISTICS

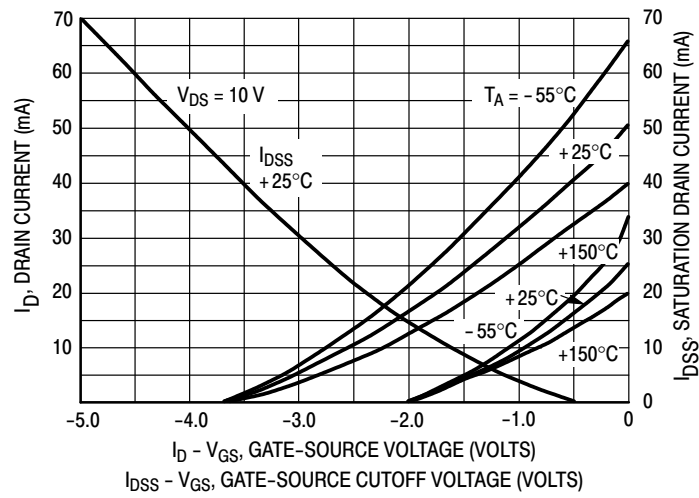
Zero–Gate–Voltage Drain Current ( $V_{DS} = 10\ \text{Vdc}$ , $V_{GS} = 0$ )	$I_{DSS}$	12 24	–	30 60	mAdc
Gate–Source Forward Voltage ( $I_G = 1.0\ \text{mAdc}$ , $V_{DS} = 0$ )	$V_{GS(f)}$	–	–	1.0	Vdc

### SMALL–SIGNAL CHARACTERISTICS

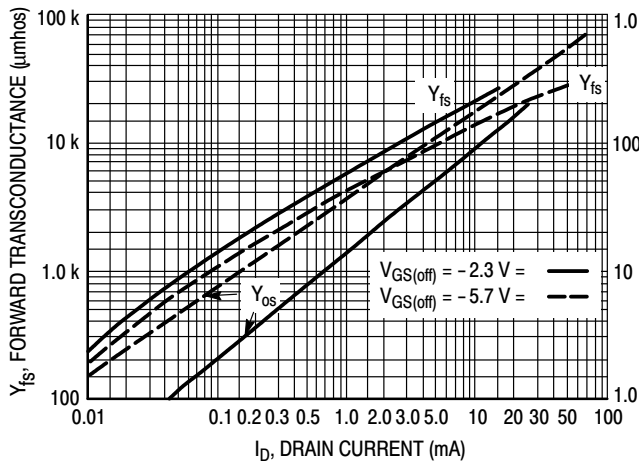
Forward Transfer Admittance ( $V_{DS} = 10\ \text{Vdc}$ , $I_D = 10\ \text{mAdc}$ , $f = 1.0\ \text{kHz}$ )	$ Y_{fs} $	8.0	–	18	mmhos
Output Admittance ( $V_{DS} = 10\ \text{Vdc}$ , $I_D = 10\ \text{mAdc}$ , $f = 1.0\ \text{kHz}$ )	$ y_{os} $	–	–	250	$\mu\text{mhos}$
Input Capacitance ( $V_{GS} = -10\ \text{Vdc}$ , $V_{DS} = 0\ \text{Vdc}$ , $f = 1.0\ \text{MHz}$ )	$C_{iss}$	–	–	5.0	pF
Reverse Transfer Capacitance ( $V_{GS} = -10\ \text{Vdc}$ , $V_{DS} = 0\ \text{Vdc}$ , $f = 1.0\ \text{MHz}$ )	$C_{rss}$	–	–	2.5	pF
Equivalent Short–Circuit Input Noise Voltage ( $V_{DS} = 10\ \text{Vdc}$ , $I_D = 10\ \text{mAdc}$ , $f = 100\ \text{Hz}$ )	$\bar{e}_n$	–	10	–	$\text{nV}/\sqrt{\text{Hz}}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

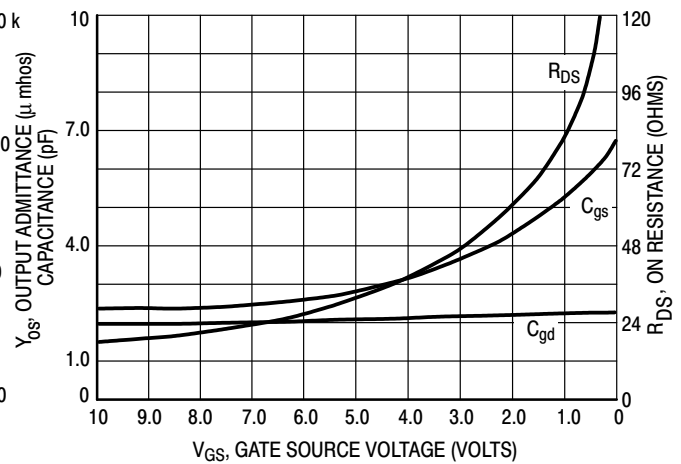
# MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ310L



**Figure 1. Drain Current and Transfer Characteristics versus Gate-Source Voltage**

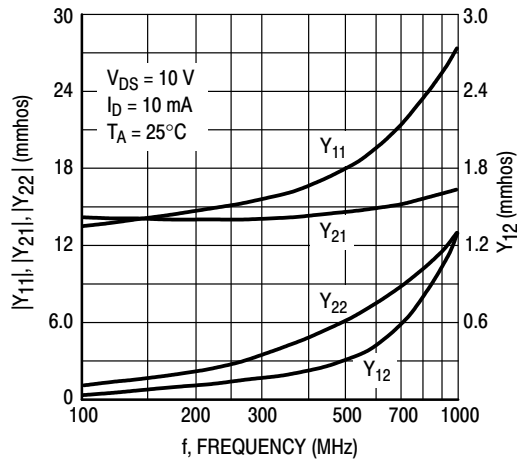


**Figure 2. Common-Source Output Admittance and Forward Transconductance versus Drain Current**

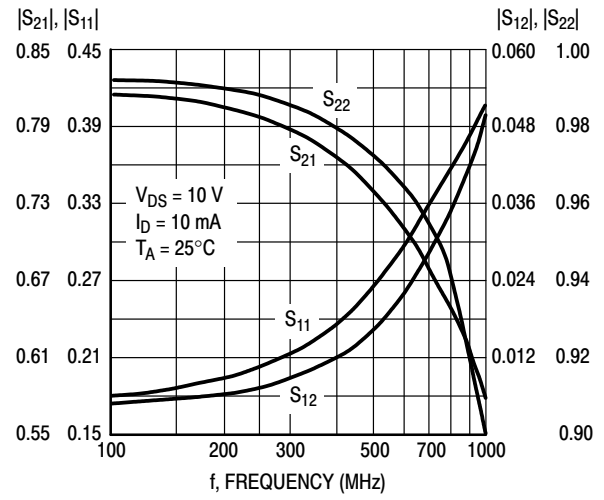


**Figure 3. On Resistance and Junction Capacitance versus Gate-Source Voltage**

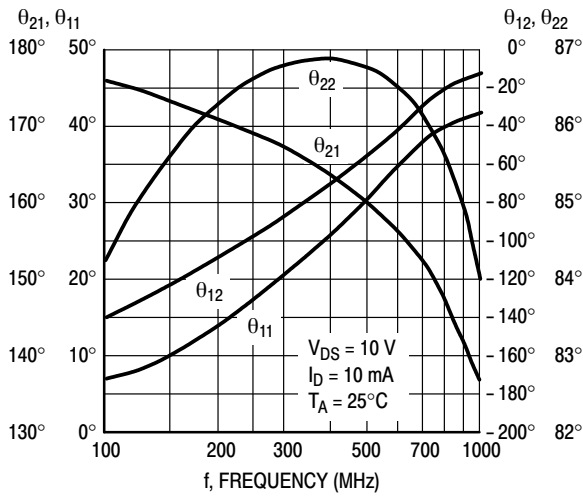
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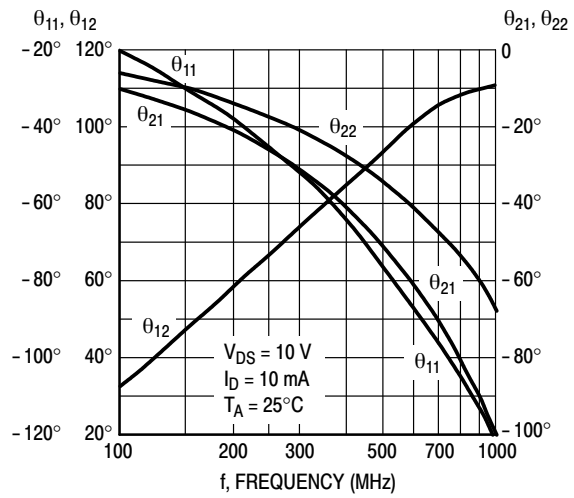
**Figure 4. Common-Gate Y Parameter Magnitude versus Frequency**



**Figure 5. Common-Gate S Parameter Magnitude versus Frequency**



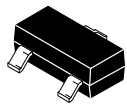
**Figure 6. Common-Gate Y Parameter Phase-Angle versus Frequency**



**Figure 7. S Parameter Phase-Angle versus Frequency**

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

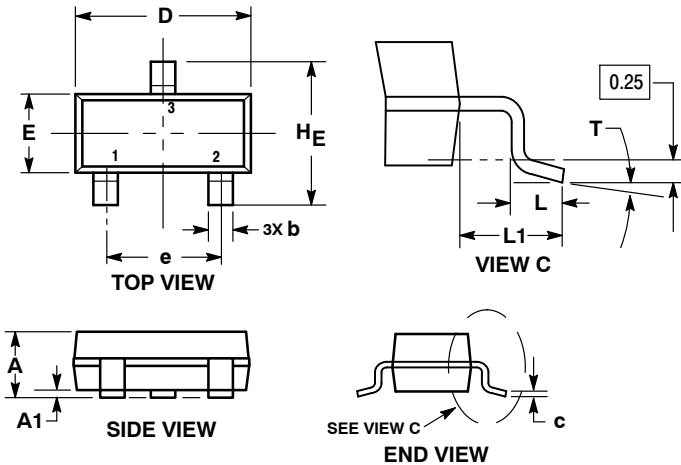
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## SOT-23 (TO-236) CASE 318-08 ISSUE AS

DATE 30 JAN 2018

SCALE 4:1

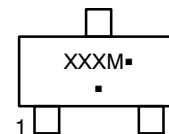


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

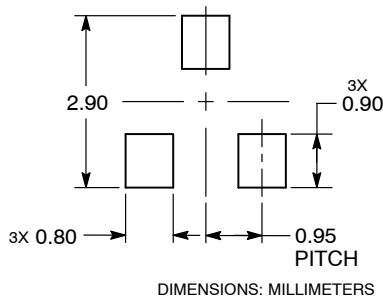
### GENERIC MARKING DIAGRAM\*



XXX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### RECOMMENDED SOLDERING FOOTPRINT



STYLE 1 THRU 5:  
CANCELLED

STYLE 6:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

STYLE 7:  
PIN 1. EMITTER  
2. BASE  
3. COLLECTOR

STYLE 8:  
PIN 1. ANODE  
2. NO CONNECTION  
3. CATHODE

STYLE 9:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 10:  
PIN 1. DRAIN  
2. SOURCE  
3. GATE

STYLE 11:  
PIN 1. ANODE  
2. CATHODE  
3. CATHODE-ANODE

STYLE 12:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 13:  
PIN 1. SOURCE  
2. DRAIN  
3. GATE

STYLE 14:  
PIN 1. CATHODE  
2. GATE  
3. ANODE

STYLE 15:  
PIN 1. GATE  
2. CATHODE  
3. ANODE

STYLE 16:  
PIN 1. ANODE  
2. CATHODE  
3. CATHODE

STYLE 17:  
PIN 1. NO CONNECTION  
2. ANODE  
3. CATHODE

STYLE 18:  
PIN 1. NO CONNECTION  
2. CATHODE  
3. ANODE

STYLE 19:  
PIN 1. CATHODE  
2. ANODE  
3. CATHODE-ANODE

STYLE 20:  
PIN 1. CATHODE  
2. ANODE  
3. GATE

STYLE 21:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

STYLE 22:  
PIN 1. RETURN  
2. OUTPUT  
3. INPUT

STYLE 23:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 24:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE

STYLE 25:  
PIN 1. ANODE  
2. CATHODE  
3. GATE

STYLE 26:  
PIN 1. CATHODE  
2. ANODE  
3. NO CONNECTION

STYLE 27:  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE

STYLE 28:  
PIN 1. ANODE  
2. ANODE  
3. ANODE

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